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(12) **United States Design Patent** (10) **Patent No.:** **US D549,189 S**  
**Misumi et al.** (45) **Date of Patent:** **\*\* Aug. 21, 2007**

(54) **DICING DIE-BONDING FILM**

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(73) Assignee: **Nitto Denko Corporation**, Osaka (JP)

(\*\*) Term: **14 Years**

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(30) **Foreign Application Priority Data**

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(51) **LOC (8) Cl.** ..... **13-03**

(52) **U.S. Cl.** ..... **D13/182**

(58) **Field of Classification Search** ..... D13/182;  
29/25.35; 156/235; 257/678, E21.505; 310/340,  
310/366; 438/113, 460

See application file for complete search history.

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(57) **CLAIM**

The ornamental design for a dicing die-bonding film, as shown and described.

**DESCRIPTION**

FIG. 1 is a front view of a dicing die-bonding film showing our new design, it being understood that the cut away portion indicates that the film has an indeterminate length wherein the pattern is repeated uniformly throughout the length thereof.

FIG. 2 is a rear view thereof.

FIG. 3 is a top plan view thereof.

FIG. 4 is a bottom plan view thereof.

FIG. 5 is a left side view thereof; and,

FIG. 6 is a right side view thereof.

The article to which the design is applied is affixed to the rear side of a semiconductor wafer with a circuit pattern formed, is diced (cut) into specified sizes together with the semiconductor wafer, and is bonded (affixed) on to the circuit substrate as it is.

The present article is formed by exfoliatively interleaving light-transmitting resin with circular patterns at the width-wise center section as well as colored patterns on the periphery and transparent resin, and measures as a whole about 230 to 400 mm wide and about 10 to 100  $\mu$ m thick, with the circular patterns at the center about 160 to 310 mm in diameter, and is continuous horizontally only in “front view” and “rear view.”

**1 Claim, 2 Drawing Sheets**

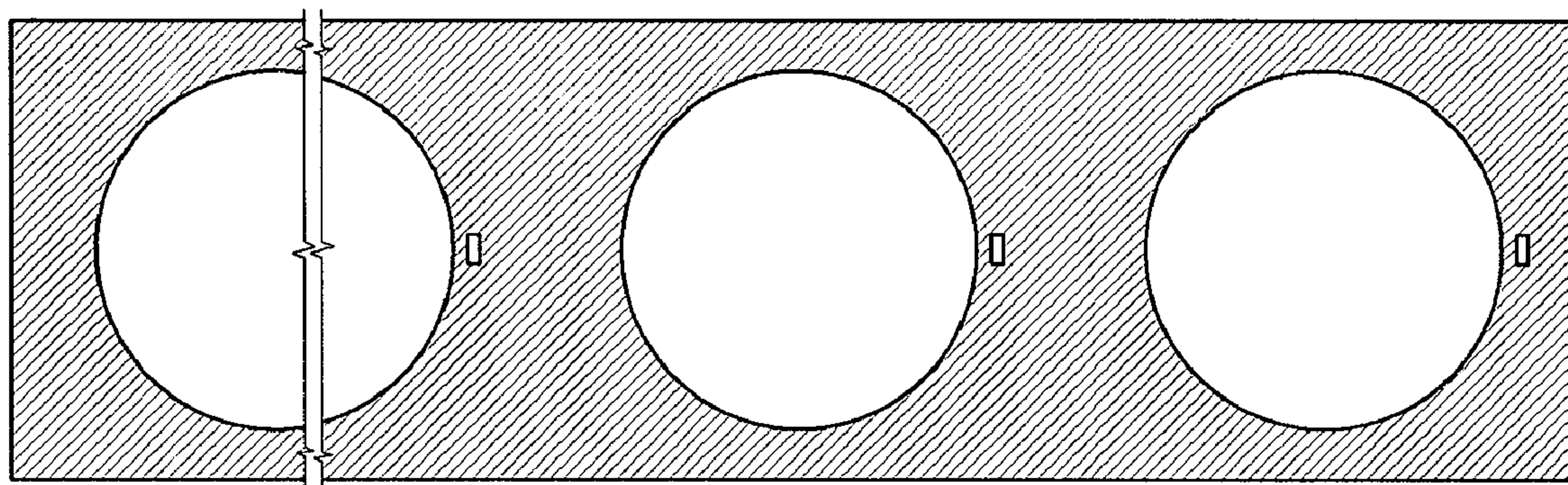




FIG. 1

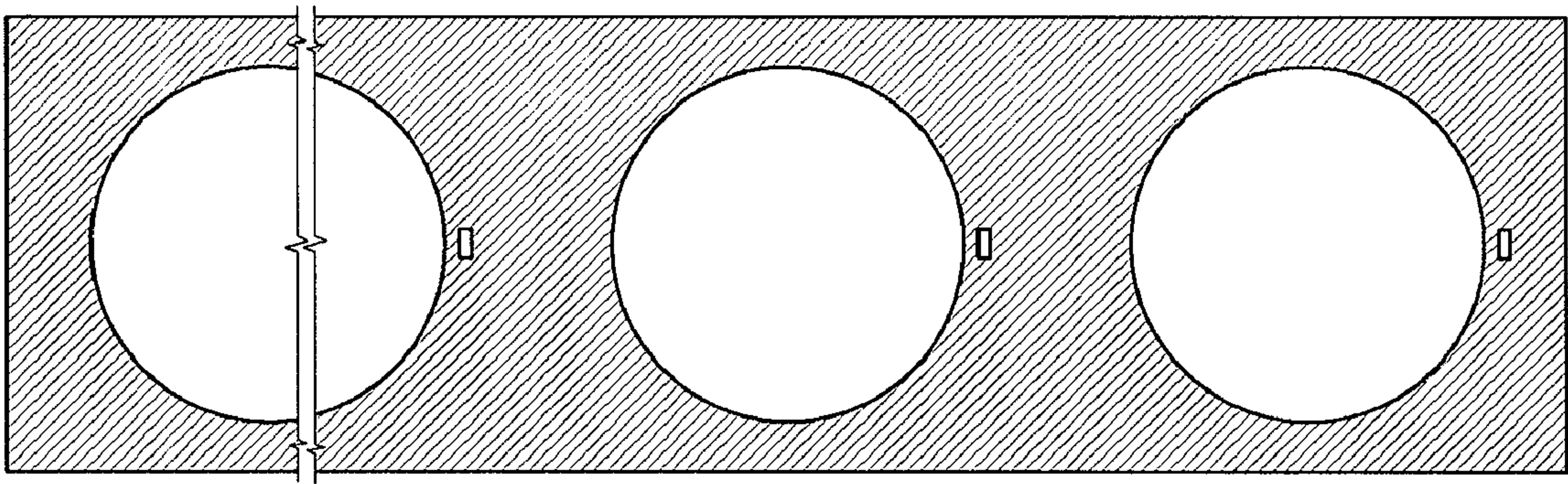


FIG. 2

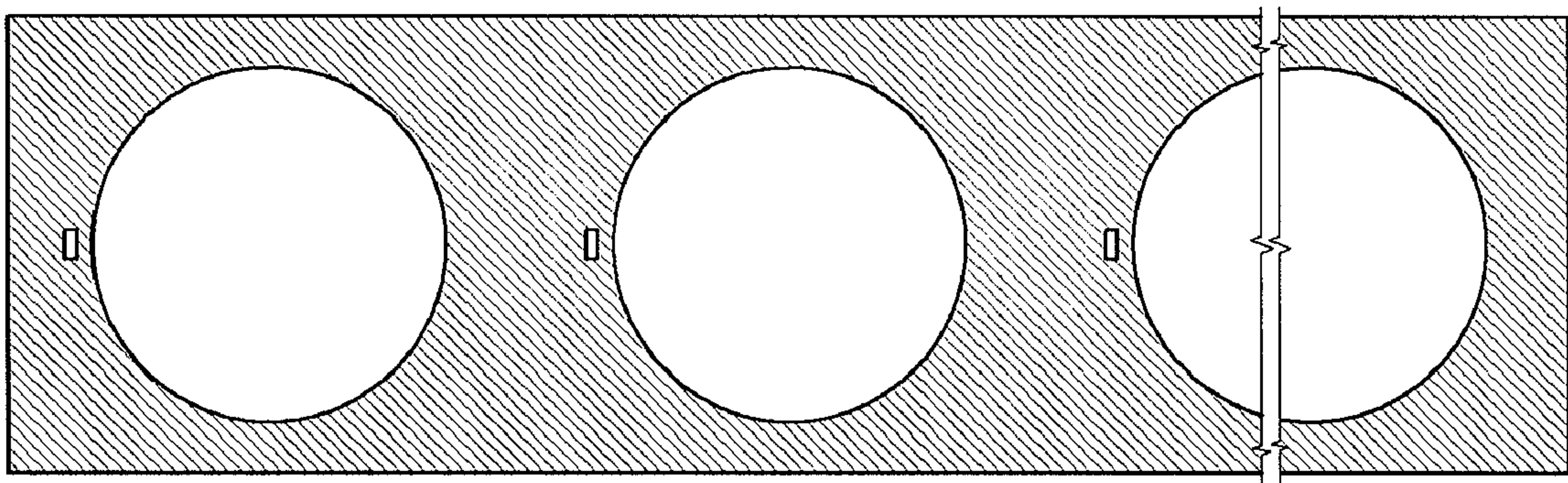


FIG. 3

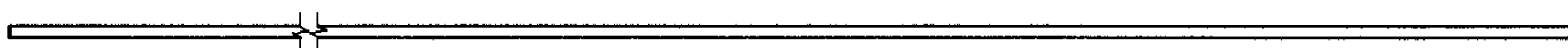
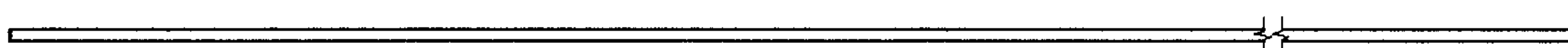


FIG. 4



*FIG. 5*



*FIG. 6*

